

HIGH EFFICIENCY MOSFETS IN DFN5060 PACKAGES



Features

- Advanced Split Gate Trench (SGT) MOSFET Technology
- Low $R_{ds(on)}$ for high efficiency and minimal power loss
- Compact, optimized DFN5060 package for superior heat dissipation
- Low thermal resistance for reliable performance
- High-density cell design (select models) for even lower $R_{ds(on)}$
- Wide operating junction temperature range up to 175°C (selected models)



Benefits

The optimized DFN5060 package and low thermal resistance provide excellent heat dissipation, ensuring stable operation even under heavy loads.

The compact 5.0 mm x 6.0 mm footprint allows for integration into dense PCB layouts and size-constrained applications.

Applications



Battery
management
systems



HVAC
systems



Industrial
equipment

MCC's High Efficiency N-Channel MOSFETs in DFN5060 Packages



**SGT MOSFETs that
deliver reliable power
switching in small
footprints**

DFN5060 package is optimized for heat dissipation and low thermal resistance



Product Attributes, Parametrics & Datasheets

Product	Type	Package	Drain Source Voltage VDS	Drain Source On-Resistance (max.) RDS(on)	Datasheet
<u>MCAC150N15Y</u>	Power MOSFET	DNF5060	150	0.15	<u>Info</u>
<u>MCAC2D7N03YL</u>	Power MOSFET	DNF5060	30	0.0027	<u>Info</u>
<u>MCAC2D6N06YL</u>	Power MOSFET	DNF5060	60	0.0026	<u>Info</u>

Applications:



Power Management & Conversion

- Battery management systems
- DC-DC converters
- Switched-mode power supplies (SMPS)



Industrial Industrial Automation & Control

- Motor controls and drivers
- Industrial equipment
- Solenoids control



Lighting & Building Automation

- Lighting control systems
- HVAC systems



Consumer & IoT Devices

- Load switching in IoT and portable devices
- Relay drivers
- Small signal amplification
- Switching circuits

CONTACT MCC TO REQUEST A SAMPLE

mccsemi.com | +818.701.4933

